Fast Recovery Diodes (FRD)

Panasonic

Unit: mm

MA3D649 (MA6D49)

Silicon planar type (cathode common)

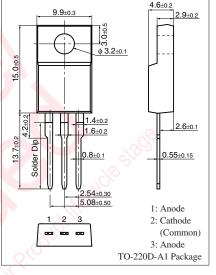
For high-frequency rectification

Features

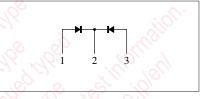
- \bullet Low forward voltage $V_{\rm F}$
- \bullet Fast reverse recovery time t_{rr}
- TO-220D (Full-pack package) with high dielectric breakdown voltage
- Easy-to-mount, caused by its V cut lead end

Parameter	Symbol	Rating	Unit			
Repetitive peak reverse voltage	V _{RRM}	200	V			
Non-repetitive peak reverse surge voltage	V _{RSM}	200	V			
Forward current (Average)	I _{F(AV)}	5	А			
Non-repetitive peak forward surge current *	I _{FSM}	30	А			
Junction temperature	Tj	-40 to +150	°C			
Storage temperature	T _{stg}	-40 to +150	°C			

■ Absolute Maximum Ratings T_a = 25°C



Internal Connection



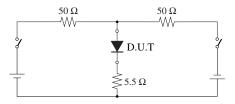
Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

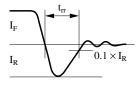
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	$I_F = 2.5 \text{ A}, \ T_C = 25^{\circ}\text{C}$, di	0-	0.98	V
Repetitive peak reverse current	GI _{RRM1}	$V_{RRM} = 200 V, T_{C} = 25^{\circ}C$	2.2		20	μA
	I _{RRM2}	$V_{RRM} = 200 \text{ V}, \ T_j = 150^{\circ}\text{C}$			2	mA
Reverse recovery time *	t _{rr}	$I_F = 1 A, I_R = 1 A$			30	ns
Thermal resistance (j-c)	R _{th(j-c)}	101 N.S.			3.0	°C/W
Thermal resistance (j-a)	R _{th(j-a)}	ist and			63	°C/W

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

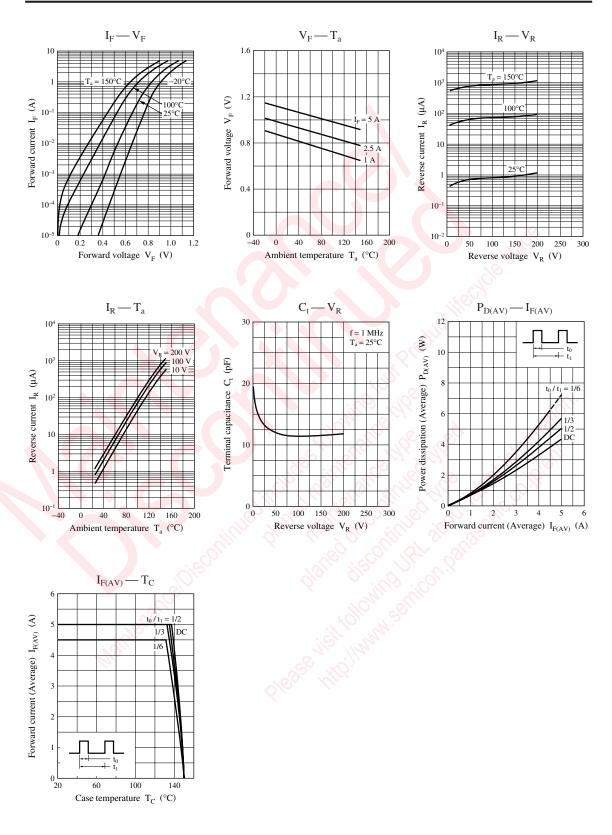
- 2. Absolute frequency of input and output is 10 MHz.
- 3. *: t_{rr} measurement circuit





Note) The part number in the parenthesis shows conventional part number.

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